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SEARCHED & SERIALIZED PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

For: FLEXIBLE BALL GRID ARRAY
CHIP SCALE PACKAGES AND
METHODS OF FABRICATION

b6
OK
to enter
SAC

Confirmation No.: 5108

Examiner: S. Clark

Group Art Unit: 2815

Attorney Docket No.: 4368US (99-0959)

Notice of Allowance Mailed:

September 30, 2002

#1410

Arnold

312

ATT

J. McMiller

1/21/03

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

December 18, 2002
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

SAC
6/19/03

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Box ISSUE FEE
Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-referenced application as follows: